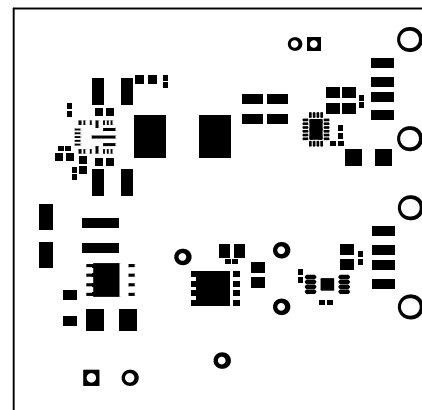
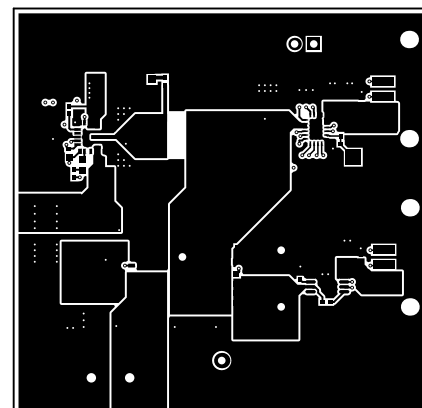


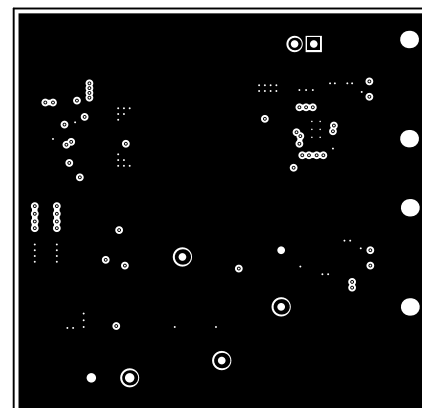
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20423	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 11/28/2017 1:57:50 PM	TEXAS INSTRUMENTS	



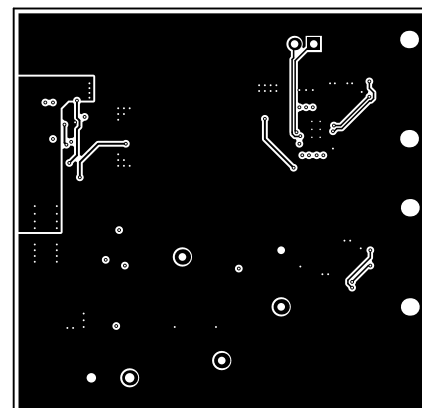
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20423	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 11/28/2017 1:57:51 PM	TEXAS INSTRUMENTS	



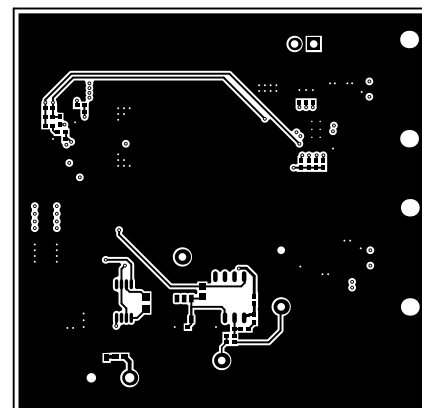
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20423	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 11/28/2017 1:57:52 PM	TEXAS INSTRUMENTS	



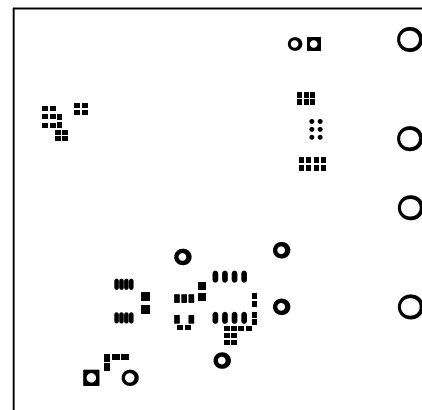
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20423	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 11/28/2017 1:57:53 PM	TEXAS INSTRUMENTS	



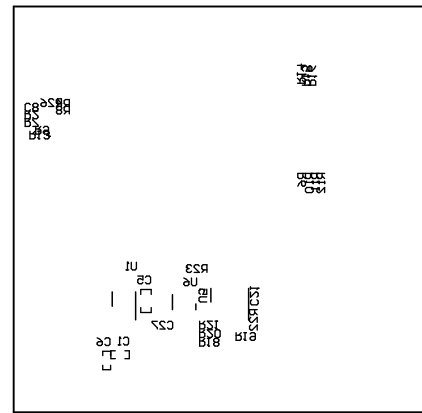
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20423	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 11/28/2017 1:57:54 PM		TEXAS INSTRUMENTS



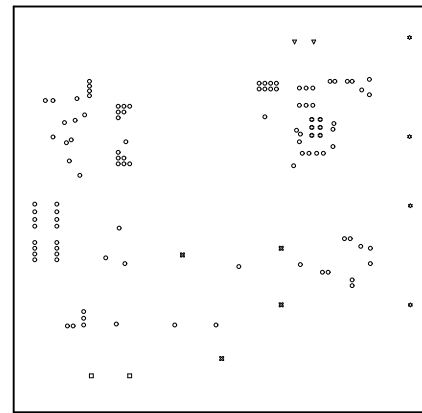
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20423	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 11/28/2017 1:57:55 PM	TEXAS INSTRUMENTS	



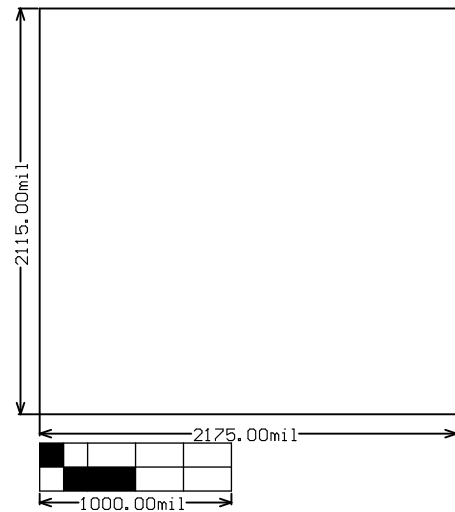
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20423	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/28/2017 1:57:56 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20423	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 11/28/2017 1:57:56 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20423	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 11/28/2017 1:57:57 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20423	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 11/28/2017 1:57:58 PM	TEXAS INSTRUMENTS	

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